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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10071320	02/08/2002	420	551	1742	Ip

**\*\*APPLICANTS:** Habu Kazutaka; Takeda Naoko;

**\*\*CONTINUING DATA VERIFIED:**  
THIS APPLICATION IS A DIV OF 09/066,851 04/28/1998

**\*\* FOREIGN APPLICATIONS VERIFIED:**  
JAPAN P08-336978 12/17/1996  
JAPAN P09-348212 12/17/1997

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		09792909-5360	
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Method to manufacture lead-free solder material having good wettability			

U.S. DEPT. OF COMM./PAT & TM-PTO-436L (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>PREPARED FOR ISSUE</b>	
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